

L Number	Hits	Search Text	DB	Time stamp
1	199	heat adj sink near5 silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:16
2	78	sheet and (heat adj sink near5 silicone)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:14
3	140	(257/625).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:16
4	747	(257/675).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:16
5	308796	silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:17
6	77	((257/675).CCLS.) and silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:30
7	759	257/E23.101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:35
8	83	silicone and 257/E23.101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:30
9	357	257/E23.107	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:37
10	157	silicone and 257/E23.107	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:36
11	39	257/E23.108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/03 10:37
-	1	lucent and lishner.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 12:30
-	871	(heat adj sink or heatsink or heat adj dissipator or heat adj dissipation) and (flipchip or flip adj chip) and planar	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 12:31
-	112	orthogonal and ((heat adj sink or heatsink or heat adj dissipator or heat adj dissipation) and (flipchip or flip adj chip) and planar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 12:38

-	19	5001548.URPN.	USPAT	2004/01/28 12:36
-	214	silicone and ((heat adj sink or heatsink or heat adj dissipator or heat adj dissipation) and (flipchip or flip adj chip) and planar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 12:39